L Number	Hits	Search Text	Ton	
1	266	electron adj beam adj microscope	DB	Time stamp
		I same and majoracope	USPAT;	2004/05/06 10:30
			US-PGPUB;	,
	ĺ	·	EPO, JPO;	
3	138	(electron adj beam adj microscope) and substrate	IBM_TDB	
		the substitute of the substitute	USPAT;	2004/05/06 10:31
			US-PGPUB;	
			EPO; JPO;	
4	74	((electron adj beam adj microscope) and substrate) and	IBM_TDB	
		wafer	USPAT;	2004/05/06 10:31
			US-PGPUB;	
			EPO; JPO;	
6 .	- 67	(((electron adj beam adj microscope) and substrate) and	IBM_TDB	
		wafer) and semiconductor	USPAT;	2004/05/06 10:32
	* -	, and Johnsonauccor	US-PGPUB;	1
			EPO; JPO;	
7	35	((((electron adj beam adj microscope) and substrate) and	IBM_TDB	
	,	wafer) and semiconductor) and inspection	USPAT;	2004/05/06 10:33
		and inspection	US-PGPUB;	
			EPO; JPO;	
10	2	(electron adj beam adj microscope) and ((low adj energy adj	IBM_TDB	
		electron adj microscope) or LEEM)	USPAT;	2004/05/06 10:35
		or adjimaroscope) of EEEIII)	US-PGPUB;	
		·	EPO; JPO;	
9	2	(((((electron adj beam adj microscope) and substrate) and	IBM_TDB	
	* }	wafer) and semiconductor) and inspection) and ((low adj	USPAT;	2004/05/06 10:46
		energy adj electron adj microscope) or LEEM)	US-PGPUB;	
		and grading the oscope of LEEM)	EPO; JPO;	
8	20	(((((electron adj beam adj microscope) and substrate) and	IBM_TDB	
	1	wafer) and semiconductor) and inspection) and review	USPAT;	2004/05/06 10:46
	. , .	and review	US-PGPUB;	
	1		EPO; JPO;	
11	2	((((((electron adj beam adj microscope) and substrate) and	IBM_TDB	
		wafer) and semiconductor) and inspection) and review) and	USPAT;	2004/05/06 10:47
		((low adj energy adj electron adj microscope) or LEEM)	US-PGPUB;	
		(Kinn and Shorish and Ciccaron and Microscope) of LEEM)	EPO; JPO;	ı
			IBM_TDB	